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1 Electrical data

1.1 Maximum ratings

Table 2. Absolute maximum ratings ($T_{CASE} = +25\text{ °C}$)

Symbol	Parameter	Value	Unit
$V_{(BR)DSS}$	Drain-source voltage	18	V
V_{GS}	Gate-source voltage	-0.5 to +15	V
I_D	Drain current	1.5	A
P_{DISS}	Power dissipation	6	W
T_J	Max. operating junction temperature	150	°C
T_{STG}	Storage temperature	-65 to +150	°C

1.2 Thermal data

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Junction - case thermal resistance	21	°C/W

2 Electrical characteristics

2.1 Static

Table 4. Static ($T_{CASE} = +25\text{ }^{\circ}\text{C}$)

Symbol	Test conditions		Min.	Typ.	Max.	Unit
I_{DSS}	$V_{GS} = 0\text{ V}$	$V_{DS} = 28\text{ V}$			1	μA
I_{GSS}	$V_{GS} = 5\text{ V}$	$V_{DS} = 0\text{ V}$			1	μA
$V_{GS(Q)}$	$V_{DS} = 10\text{ V}$	$I_D = 250\text{ }\mu\text{A}$	2.0	3.0	5.0	V
$V_{DS(ON)}$	$V_{GS} = 10\text{ V}$	$I_D = 0.4\text{ A}$		0.6		V
C_{ISS}	$V_{GS} = 0\text{ V}$	$V_{DS} = 7\text{ V}$		14.7		pF
C_{OSS}	$V_{GS} = 0\text{ V}$	$V_{DS} = 7\text{ V}$		13.3		pF
C_{RSS}	$V_{GS} = 0\text{ V}$	$V_{DS} = 7\text{ V}$		1.3		pF

2.2 Dynamic

Table 5. Dynamic

Symbol	Test conditions	Min.	Typ.	Max.	Unit
P_{OUT}	$V_{DD} = 7.5\text{ V}$, $I_{DQ} = 50\text{ mA}$, $P_{IN} = 17\text{ dBm}$, $f = 870\text{ MHz}$	30	31		dBm
G_{PS}	$V_{DD} = 7.5\text{ V}$, $I_{DQ} = 50\text{ mA}$, $P_{OUT} = 30\text{ dBm}$, $f = 870\text{ MHz}$	13	15		dB
h_D	$V_{DD} = 7.5\text{ V}$, $I_{DQ} = 50\text{ mA}$, $P_{IN} = 17\text{ dBm}$, $f = 870\text{ MHz}$	55	60		%
Load mismatch	$V_{DD} = 7.5\text{ V}$, $I_{DQ} = 50\text{ mA}$, $P_{OUT} = 1\text{ W}$, $f = 870\text{ MHz}$ All phase angles	20:1			VSWR

2.3 ESD protection characteristics

Table 6. ESD protection characteristics

Test conditions	Class
Human body model	2
Machine model	M3

2.4 Moisture sensitivity level

Table 7. Moisture sensitivity level

Test methodology	Rating
J-STD-020B	MSL 3

3 Impedance

Figure 2. Current conventions

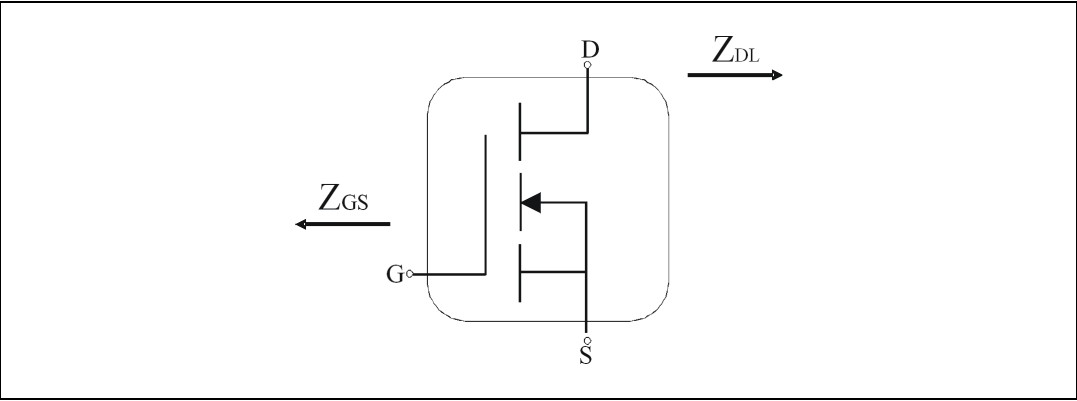


Table 8. Impedance data

Freq. (MHz)	$Z_{GS} (\Omega)$	$Z_{DL}(\Omega)$
920	$4.0 + j4.3$	$3.7 + j6.2$
900	$3.6 + j4.3$	$3.9 + j5.5$
880	$3.3 + j4.1$	$4.1 + j4.7$
860	$3.1 + j3.7$	$4.3 + j4.0$
840	$2.9 + j3.4$	$4.5 + j3.2$
820	$2.8 + j3.0$	$4.8 + j2.4$
800	$2.7 + j2.5$	$5.0 + j1.6$

4 Typical performance

Figure 3. V_{GS} vs I_D

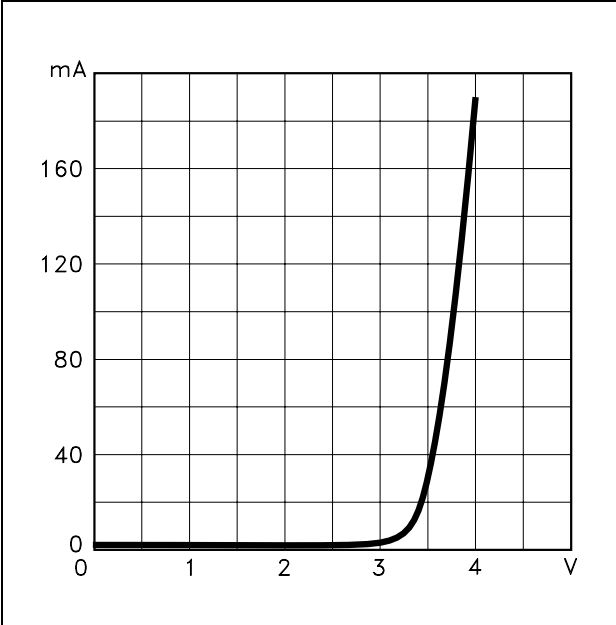


Figure 4. DC output characteristics

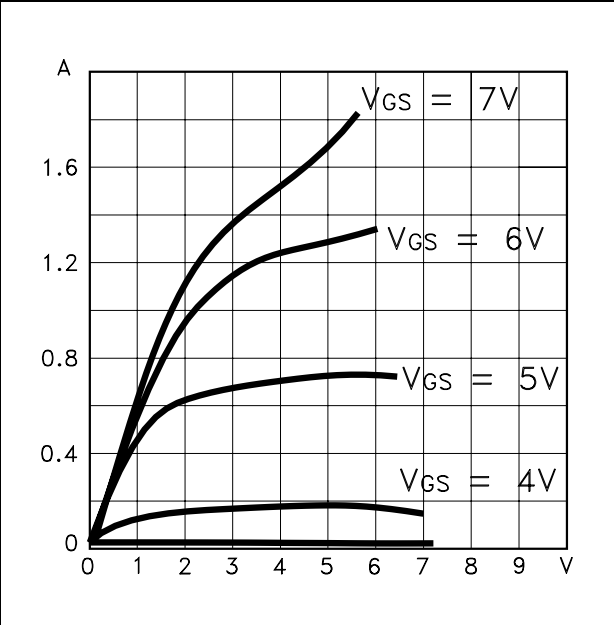


Figure 5. C_{RSS} vs V_{DS}

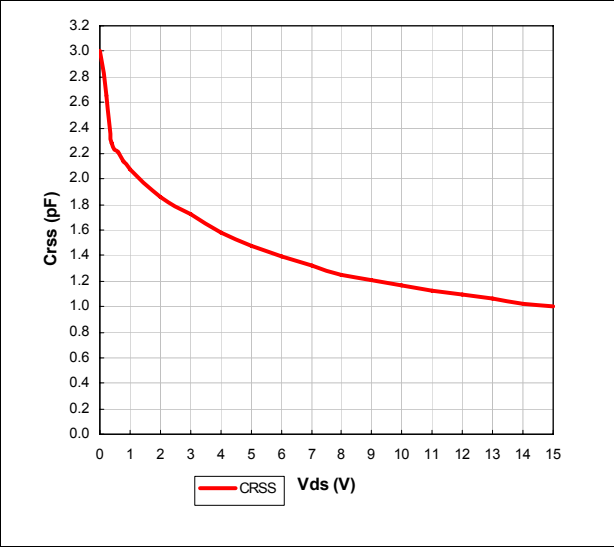


Figure 6. C_{ISS} vs V_{DS}

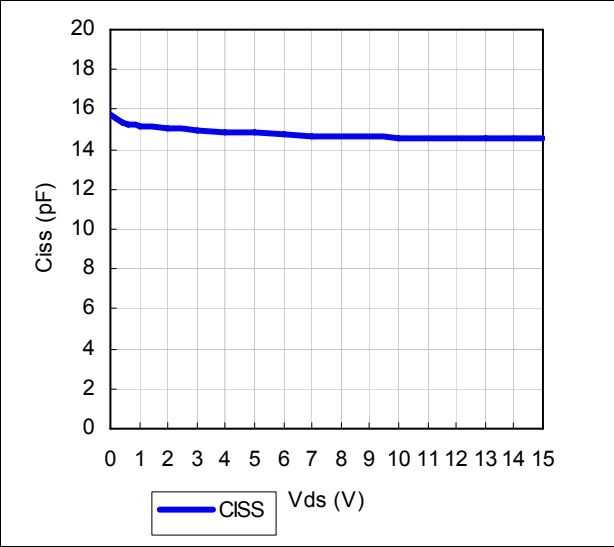


Figure 7. C_{OSS} VS V_{DS}

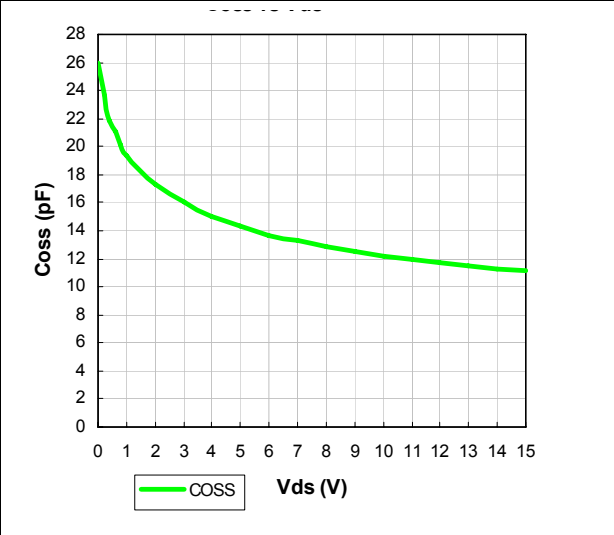


Figure 8. Gain vs output power and frequency

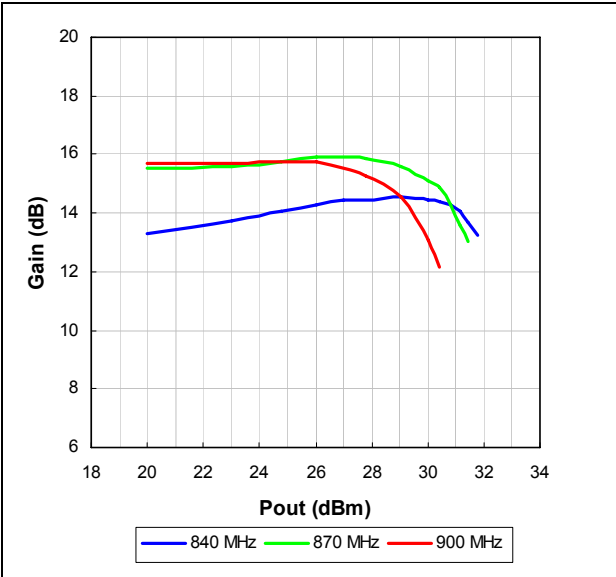


Figure 9. Output power vs input power and frequency

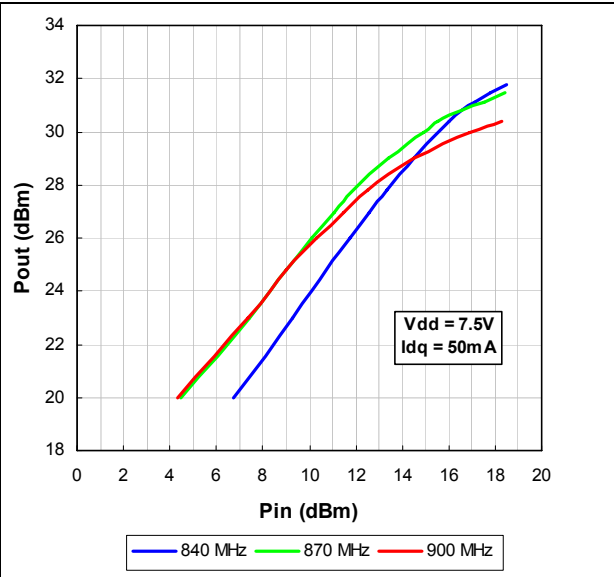


Figure 10. Efficiency vs output power and frequency

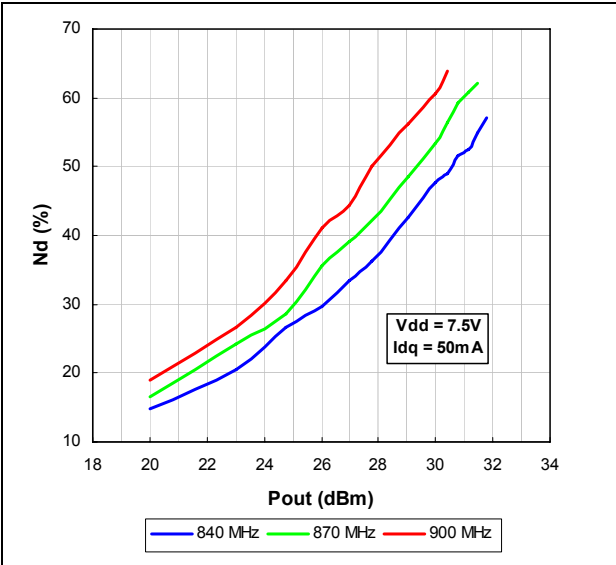


Figure 11. Gain and efficiency vs frequency

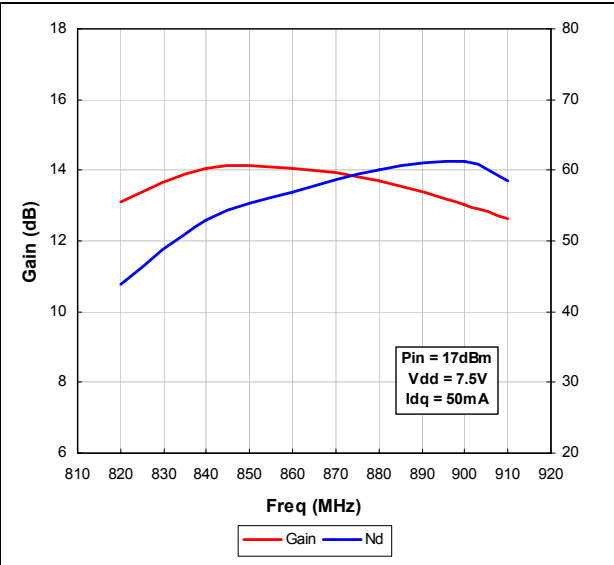


Figure 12. Input return loss vs frequency

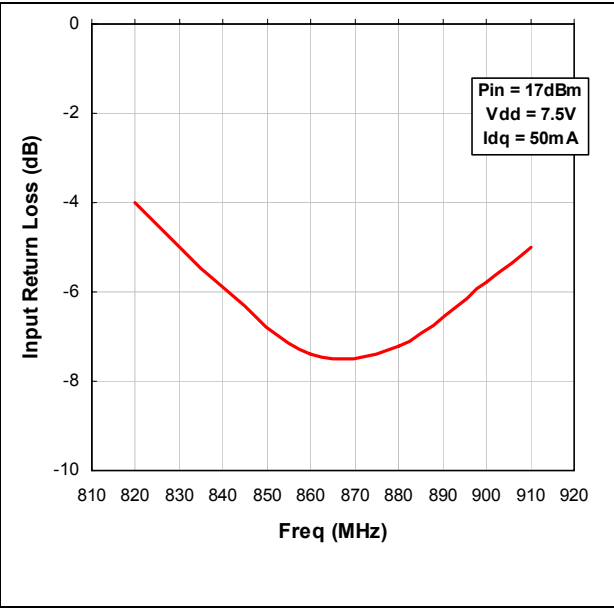


Figure 13. Output power vs input power and V_{DD}

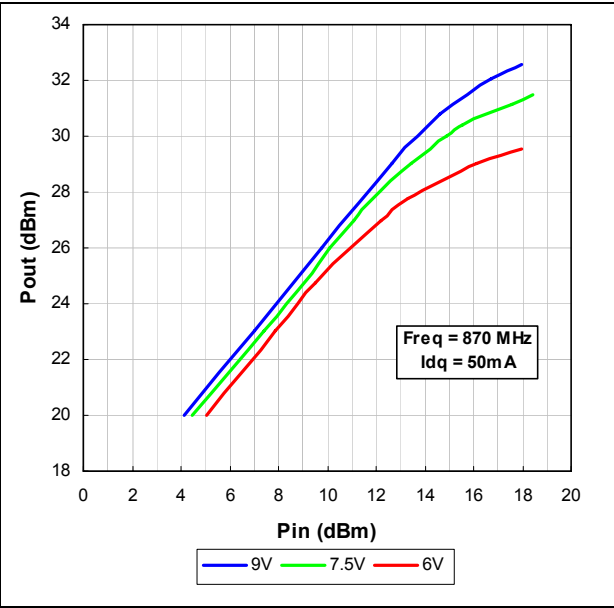


Figure 14. Efficiency vs output power and V_{DD}

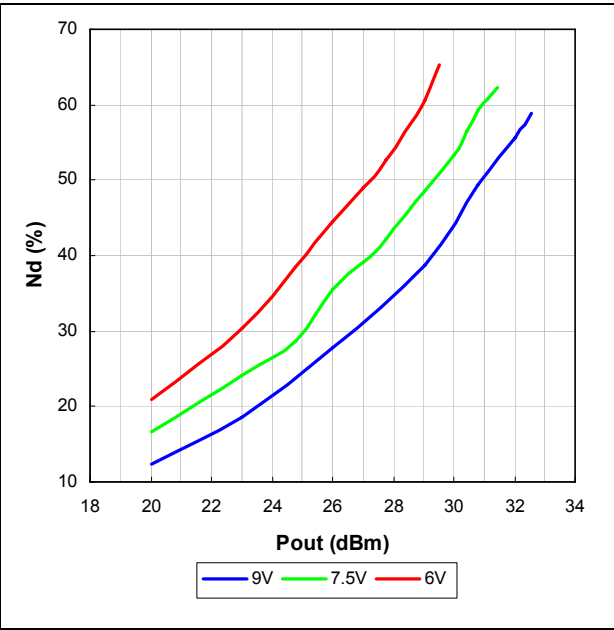


Figure 15. Output power and drain current vs drain supply voltage

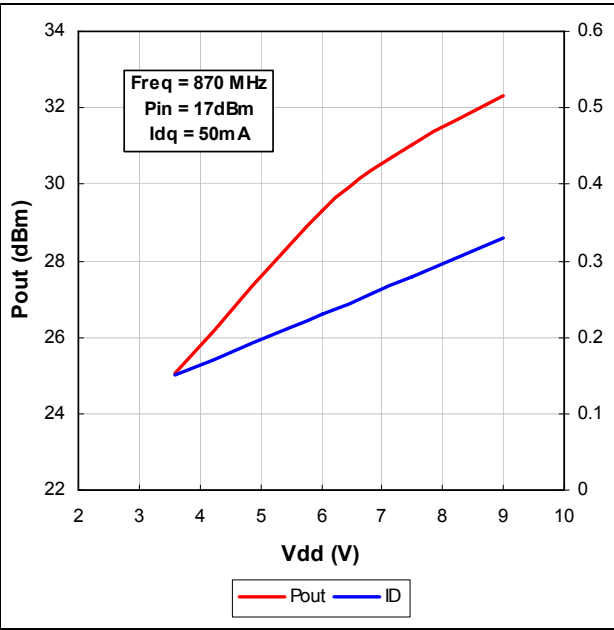
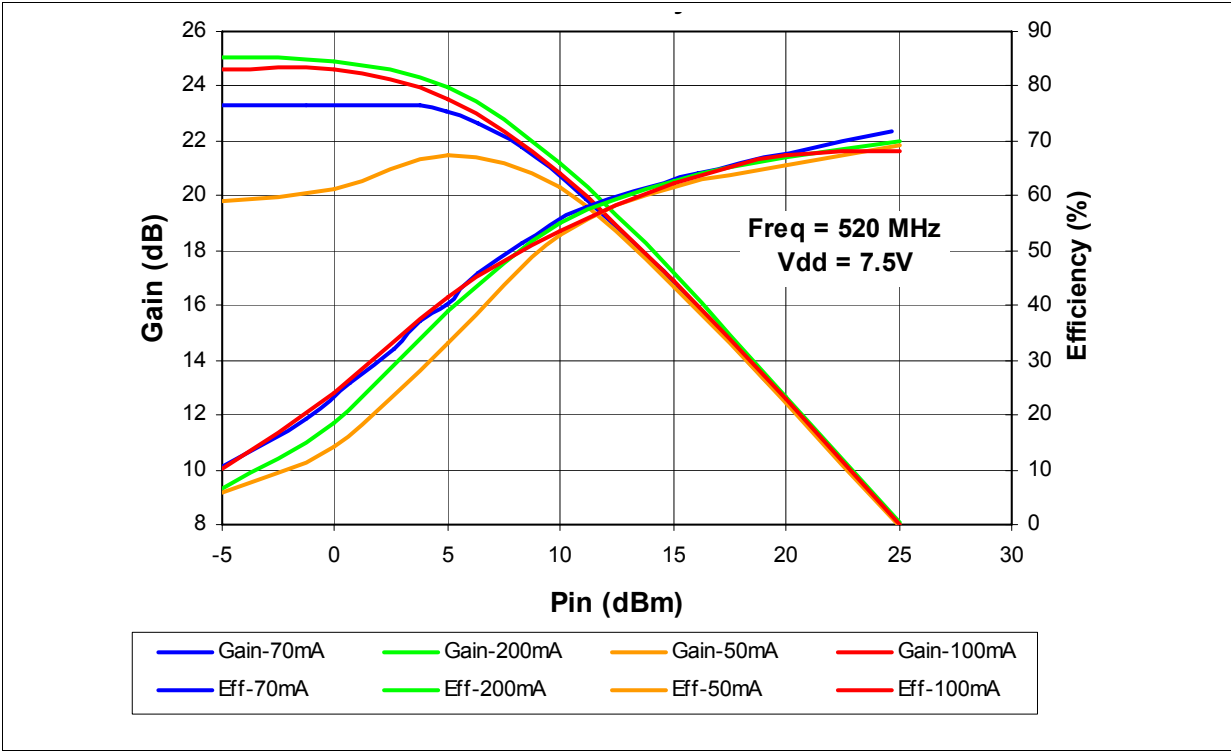
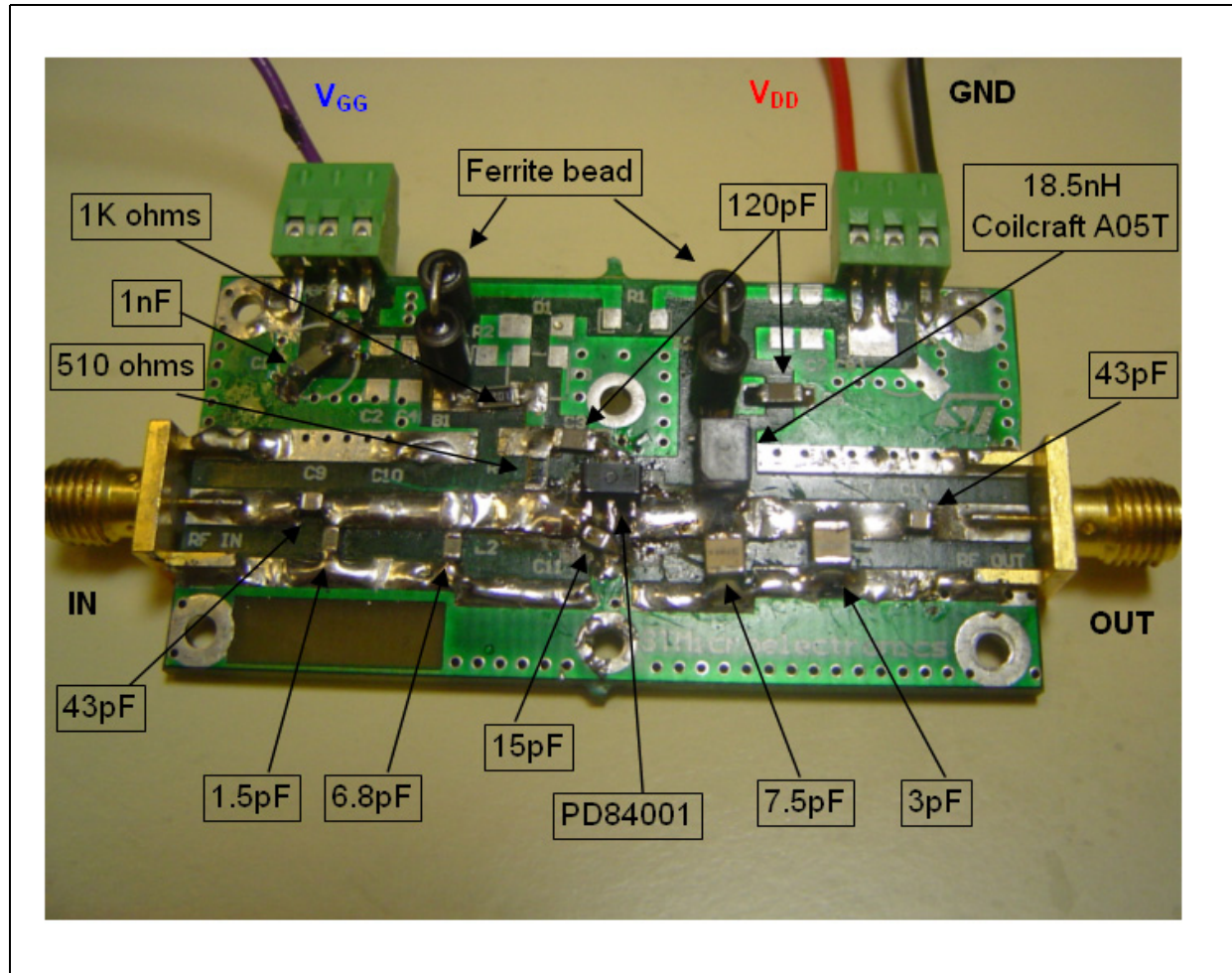


Figure 16. Gain and efficiency vs pin



5 Test circuit

Figure 17. Test circuit schematic / 840-900 MHz

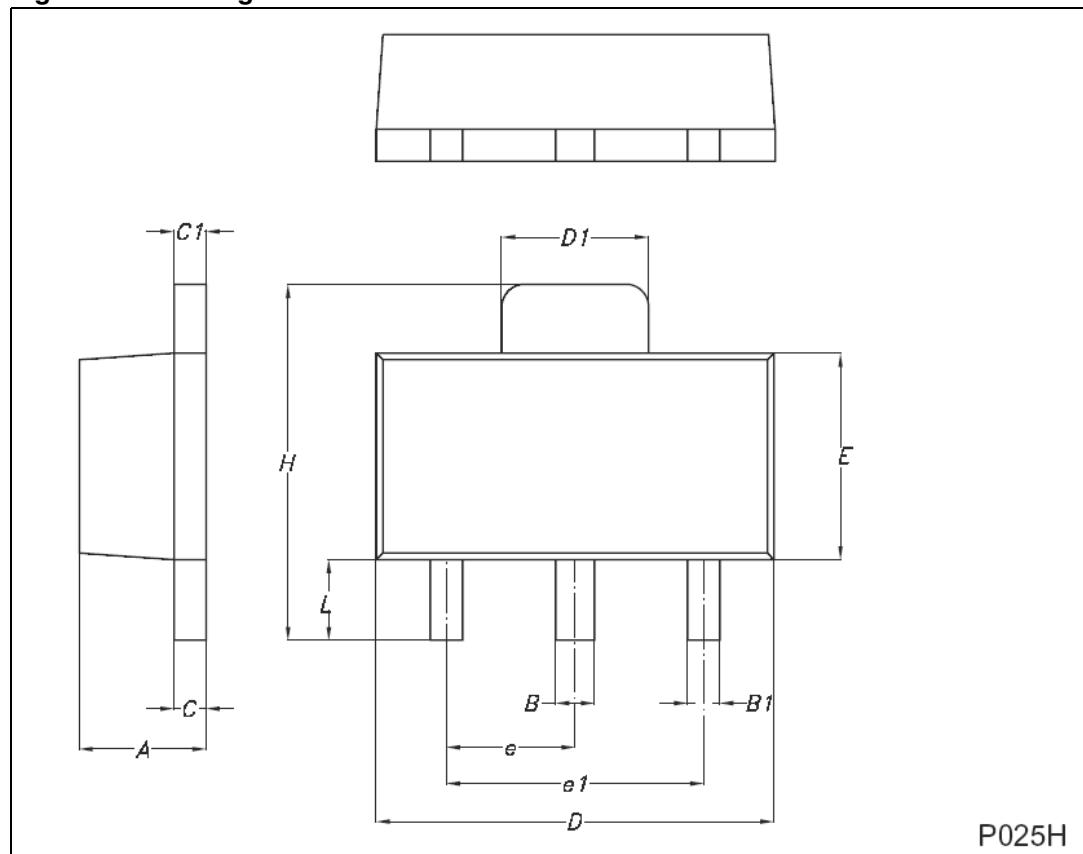


6 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

Table 9. SOT-89 mechanical data

Dim.	mm.			Inch		
	Min	Typ	Max	Min	Typ	Max
A	1.4		1.6	55.1		63.0
B	0.44		0.56	17.3		22.0
B1	0.36		0.48	14.2		18.9
C	0.35		0.44	13.8		17.3
C1	0.35		0.44	13.8		17.3
D	4.4		4.6	173.2		181.1
D1	1.62		1.83	63.8		72.0
E	2.29		2.6	90.2		102.4
e	1.42		1.57	55.9		61.8
e1	2.92		3.07	115.0		120.9
H	3.94		4.25	155.1		167.3
L	0.89		1.2	35.0		47.2

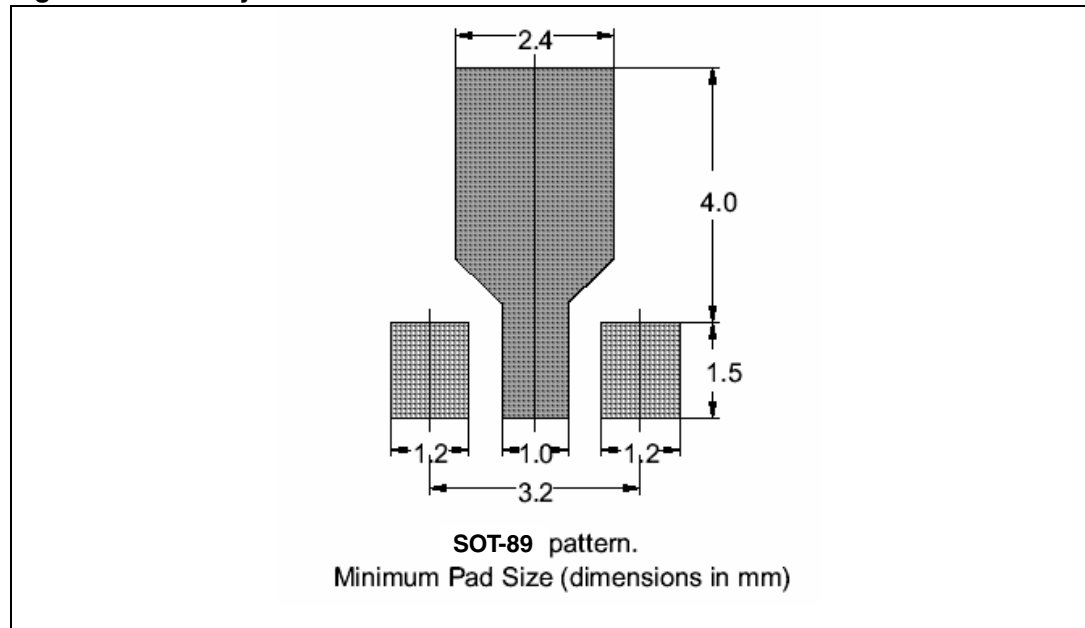
Figure 18. Package dimensions

6.1 Thermal pad and via design

Thermal vias are required in the PCB layout to effectively conduct heat away from the package. The via pattern has been designed to address thermal, power dissipation and electrical requirements of the device.

The via pattern is based on thru-hole vias with 0.203 mm to 0.330 mm finished hole size on a 0.5 mm to 1.2 mm grid pattern with 0.025 plating on via walls. If micro vias are used in a design, it is suggested that the quantity of vias be increased by a 4:1 ratio to achieve similar results.

Figure 19. Pad layout details



6.2 Soldering profile

Figure 20 shows the recommended solder for devices that have Pb-free terminal plating and where a Pb-free solder is used.

Figure 20. Recommended solder profile

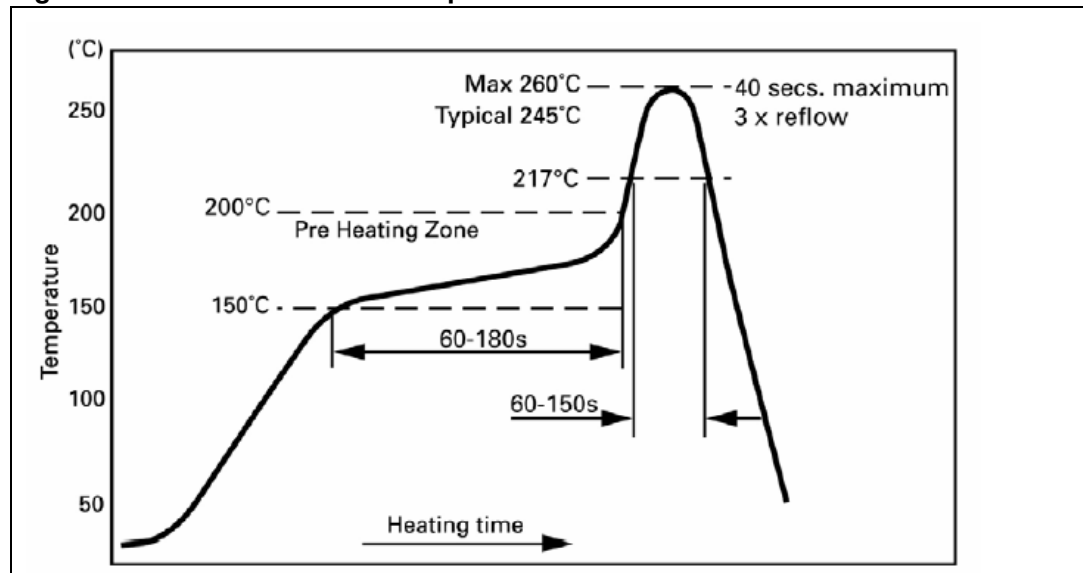


Figure 21 shows the recommended solder for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.

Figure 21. Recommended solder profile for leaded devices

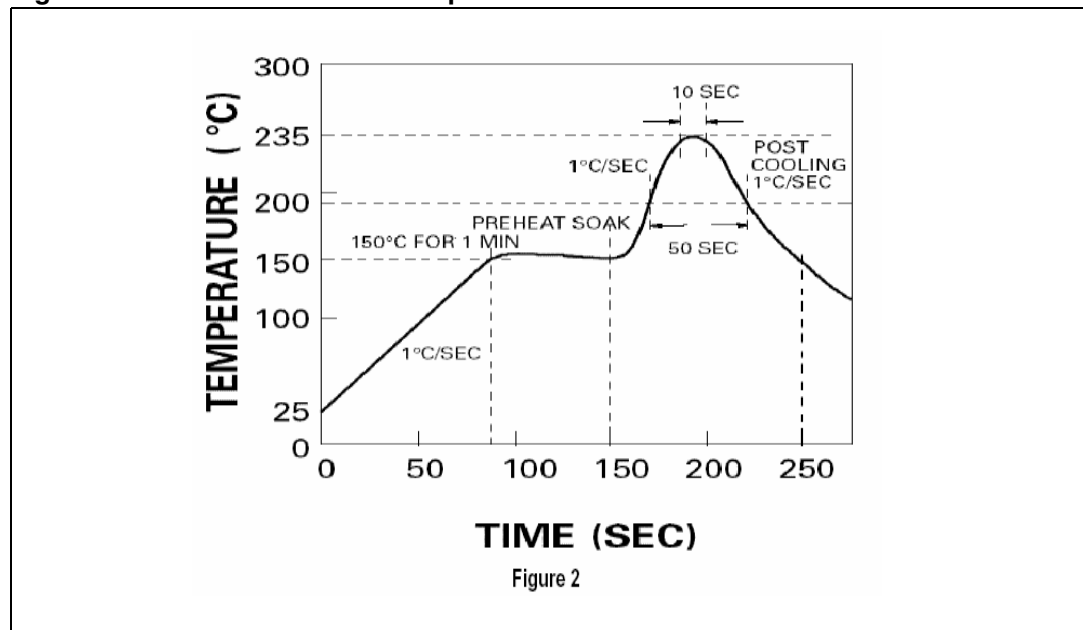
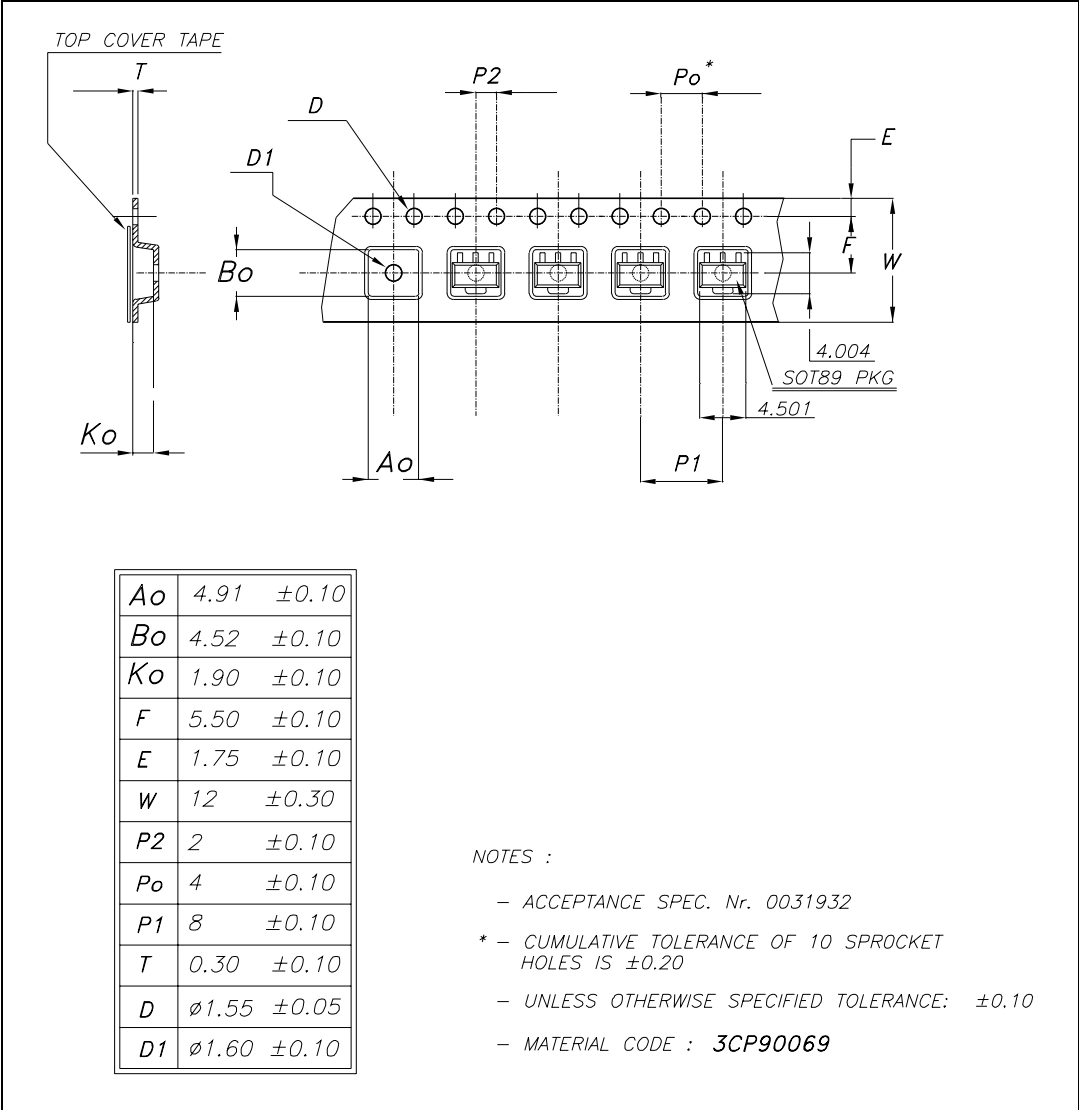


Figure 22. Reel information



7 Revision history

Table 10. Document revision history

Date	Revision	Changes
06-Dec-2006	1	Initial release
16-May-2007	2	Marking updated
05-Jun-2007	3	Part number update
25-Aug-2008	4	Updated Table 4 on page 4

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